



N - CHANNEL ENHANCEMENT MODE POWER MOSFET

TF030N03N

• General Description

The TF030N03N uses advanced trench technology and design to provide excellent RDS(ON) with low gate charge. It can be used in a wide variety of applications.

• Features

Advance device construction

Low $R_{DS(ON)}$ to minimize conduction loss

Low Gate Charge for fast switching

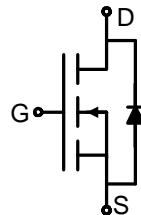
Low Thermal resistance

• Application

Synchronous Rectification for AC-DC/DC-DC converter

Power Tools

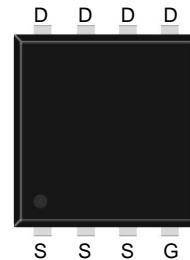
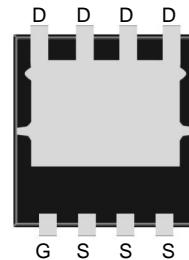
• Product Summary



$V_{DS} = 30V$

$R_{DS(ON)} = 3.2m\Omega$

$I_D = 90A$



PDFNWB5x6-8L

• Package Marking and Ordering Information:

Part NO.	TF030N03N
Marking	TF030N03N
Packing Information	---
Basic ordering unit (pcs)	5000

• Absolute Maximum Ratings ($T_C = 25^\circ C$)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	$I_D @ T_C = 25^\circ C$	90	A
	$I_D @ T_C = 75^\circ C$	70	A
	$I_D @ T_C = 100^\circ C$	60	A
Pulsed Drain Current ^①	I_{DM}	210	A
Total Power Dissipation	$P_D @ T_C = 25^\circ C$	65	W
Total Power Dissipation	$P_D @ T_A = 25^\circ C$	2.0	W
Operating Junction Temperature	T_J	-55 to 150	$^\circ C$
Storage Temperature	T_{STG}	-55 to 150	$^\circ C$
Single Pulse Avalanche Energy	E_{AS}	175	mJ



Shenzhen Tuofeng Semiconductor Technology Co., Ltd

N - CHANNEL ENHANCEMENT MODE POWER MOSFET

TF030N03N

• Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R _{thJC}	-	-	1.9	° C/W
Thermal resistance, junction - ambient	R _{thJA}	-	-	50	° C/W
Soldering temperature, wavesoldering for 8 s	T _{sold}	-	-	265	° C

• Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D = 250μA	30	-	-	V
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = 250μA	1.1	1.5	2.1	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =30 V _{GS} = 0V	-	-	1.0	μA
Gate- Source Leakage Current	I _{GSS}	V _{GS} =±20V , V _{DS} = 0V	-	-	±100	nA
Static Drain-source On Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =30A	-	3.2	3.7	mΩ
		V _{GS} =4.5V, I _D =25A	-	4.0	4.5	mΩ
Forward Transconductance	g _{FS}	V _{DS} = 25V, I _D =20A	-	32	-	S
Source-drain voltage	V _{SD}	I _S =20A	-	-	1.20	V

• Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C _{iss}	f = 1MHz V _{DS} =15V V _{GS} = 0V	-	2987	-	pF
Output capacitance	C _{oss}		-	429	-	
Reverse transfer capacitance	C _{rss}		-	368	-	

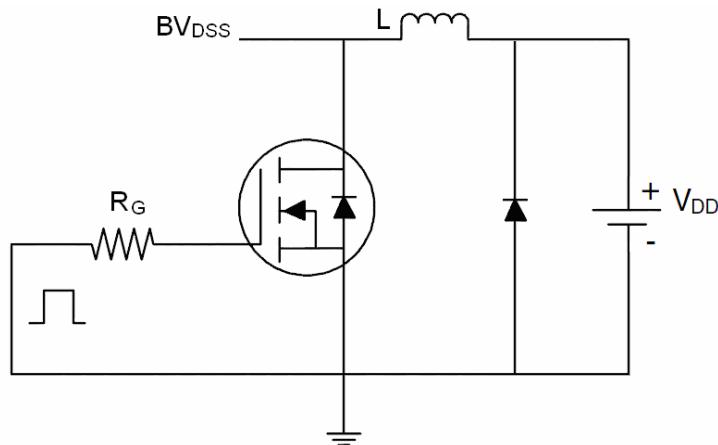
• Gate Charge characteristics(T_a = 25°C)

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Total gate charge	Q _g	V _{DD} = 15V I _D = 20A V _{GS} = 10V	-	70	-	nC
Gate - Source charge	Q _{gs}		-	8.8	-	
Gate - Drain charge	Q _{gd}		-	16.3	-	

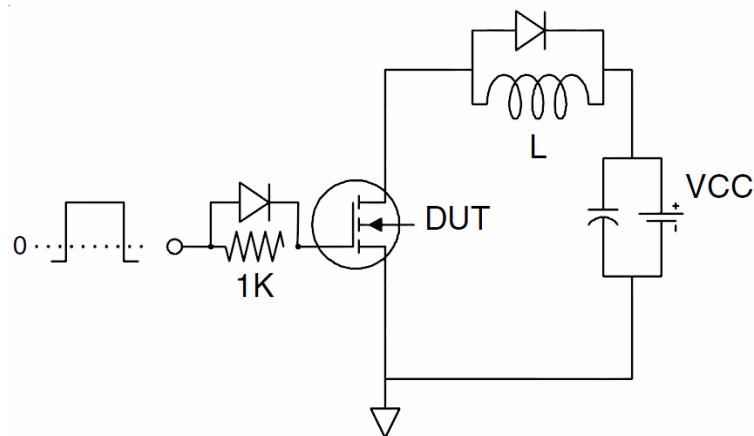
Note: ① Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2% ;

Test Circuit

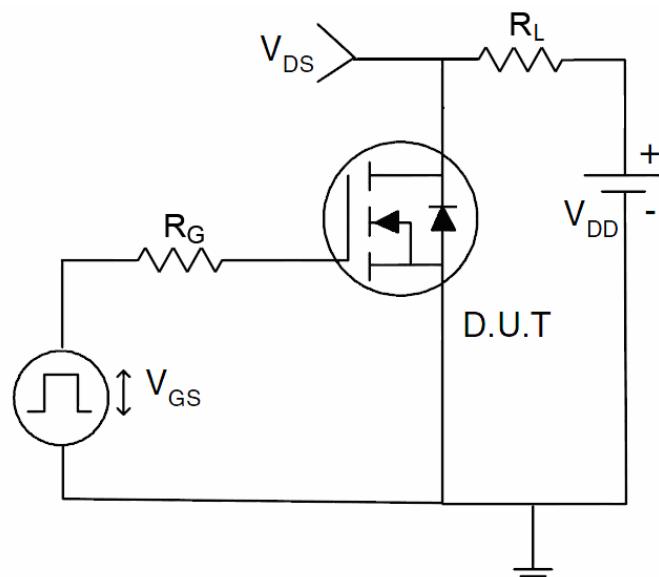
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit



Typical Electrical and Thermal Characteristics

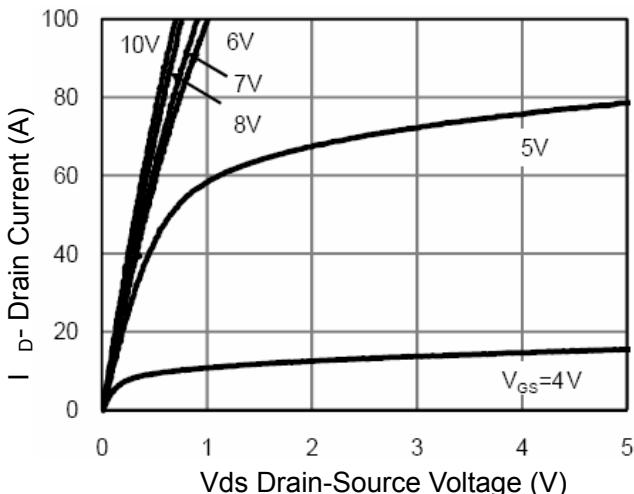


Figure 1 Output Characteristics

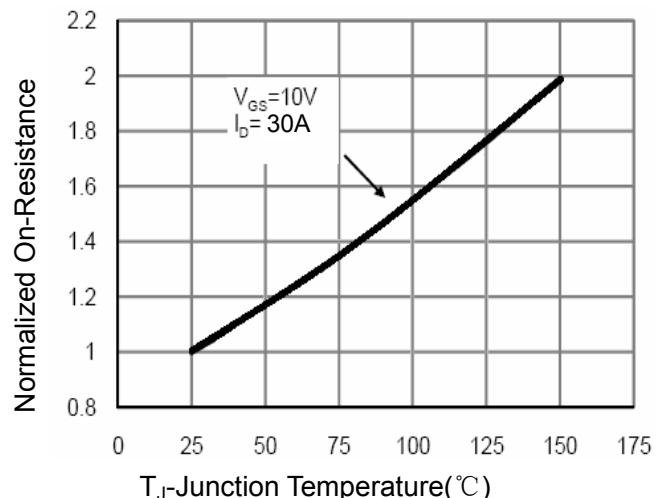


Figure 4 Rdson-JunctionTemperature

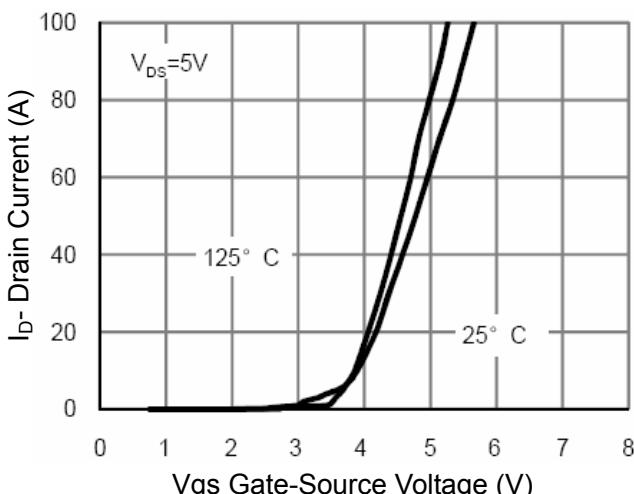


Figure 2 Transfer Characteristics

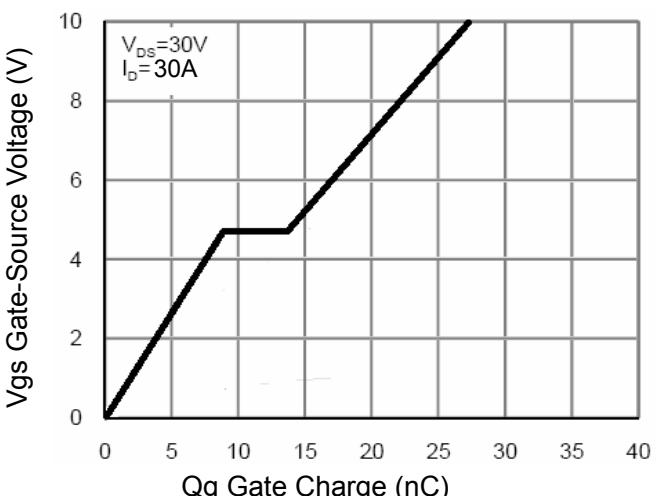


Figure 5 Gate Charge

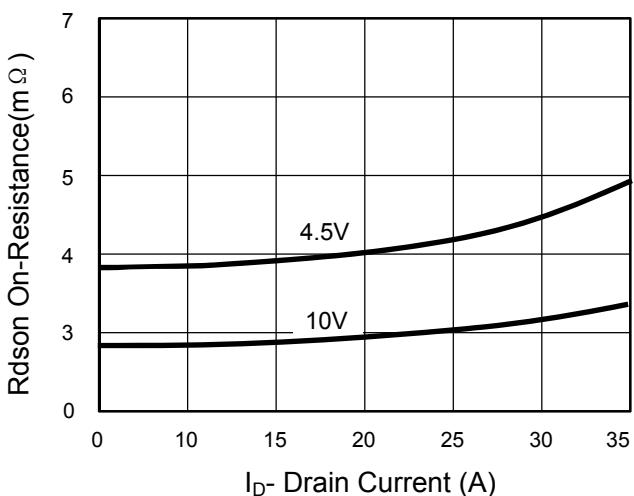


Figure 3 Rdson- Drain Current

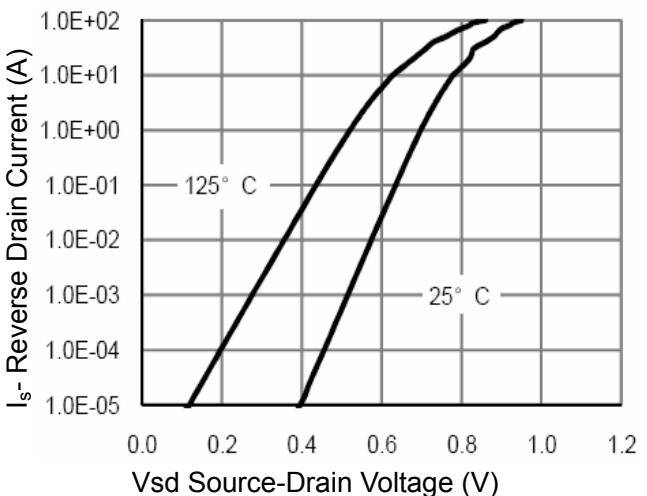


Figure 6 Source- Drain Diode Forward

N - CHANNEL ENHANCEMENT MODE POWER MOSFET

TF030N03N

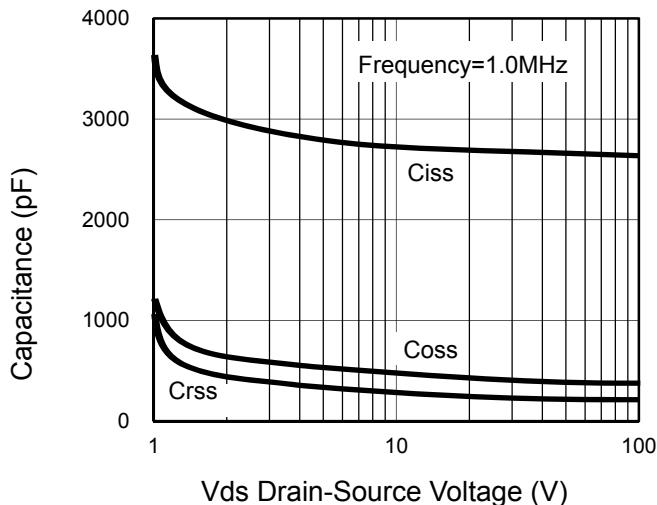


Figure 7 Capacitance vs Vds

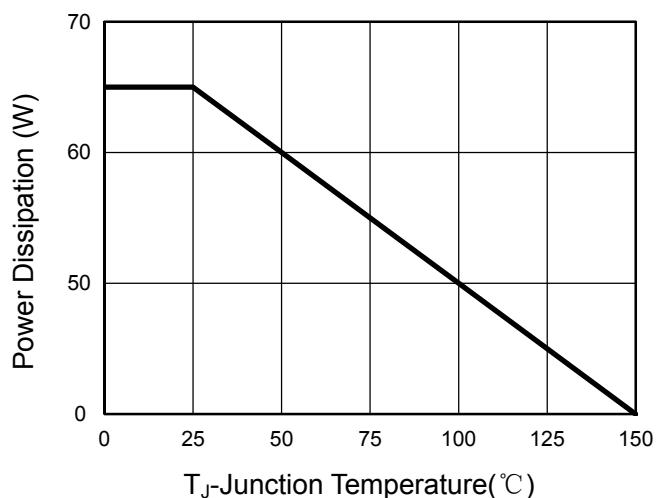


Figure 9 Power De-rating

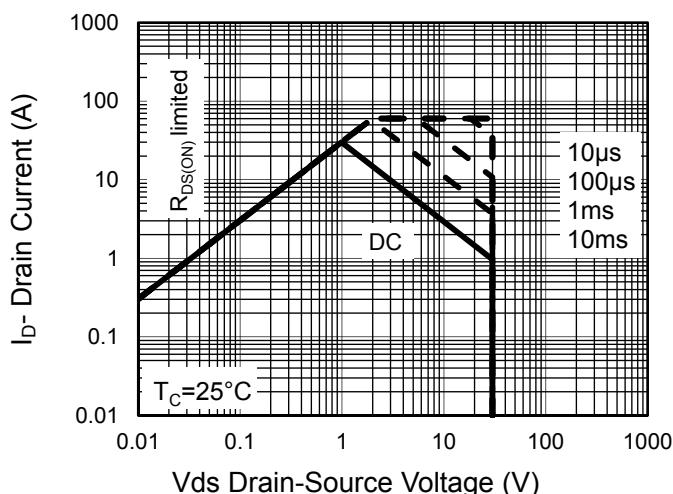


Figure 8 Safe Operation Area

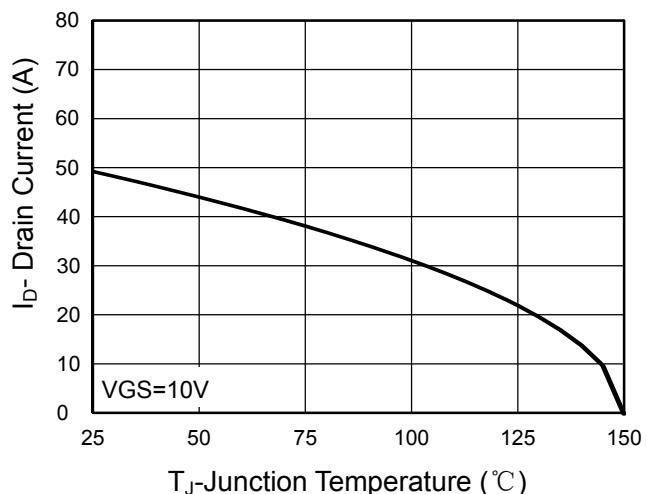


Figure 10 Current De-rating

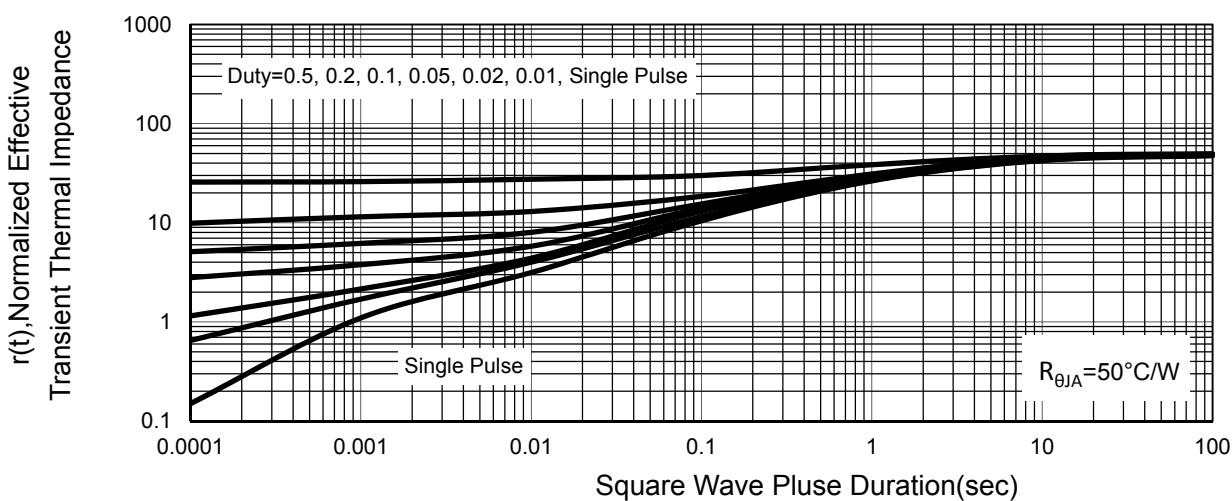


Figure 11 Normalized Maximum Transient Thermal Impedance

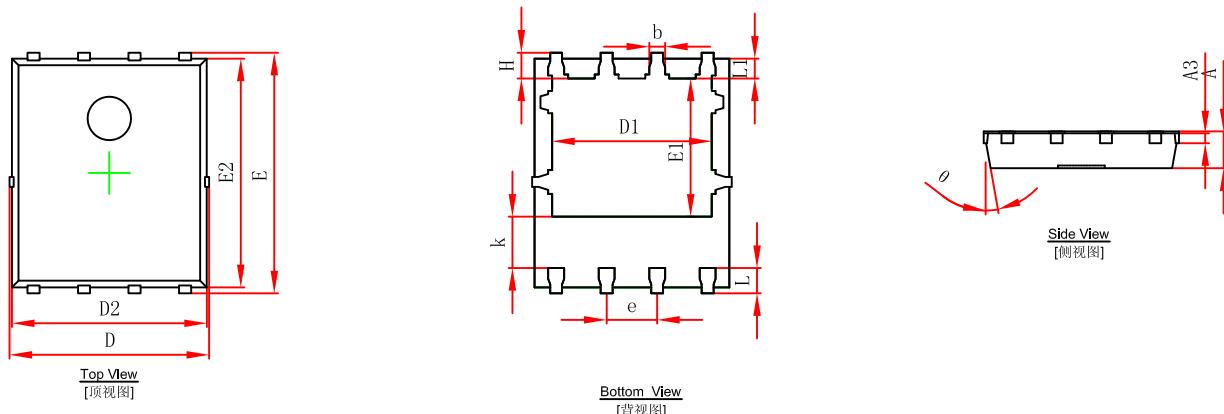


Shenzhen Tuofeng Semiconductor Technology Co., Ltd

N - CHANNEL ENHANCEMENT MODE POWER MOSFET

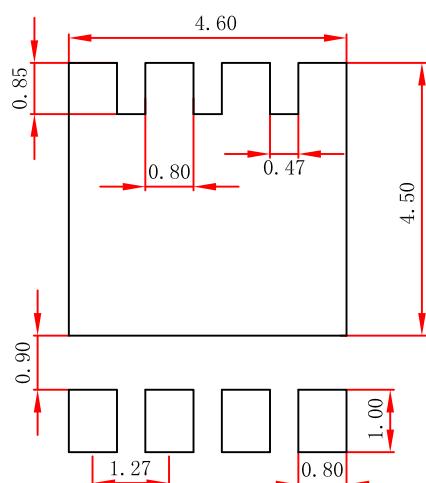
TF030N03N

PDFNWB5x6-8L Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°

PDFNWB5x6-8L Suggested Pad Layout



Note:
1. Controlling dimension:in millimeters.
2.General tolerance: $\pm 0.05\text{mm}$.
3.The pad layout is for reference purposes only.